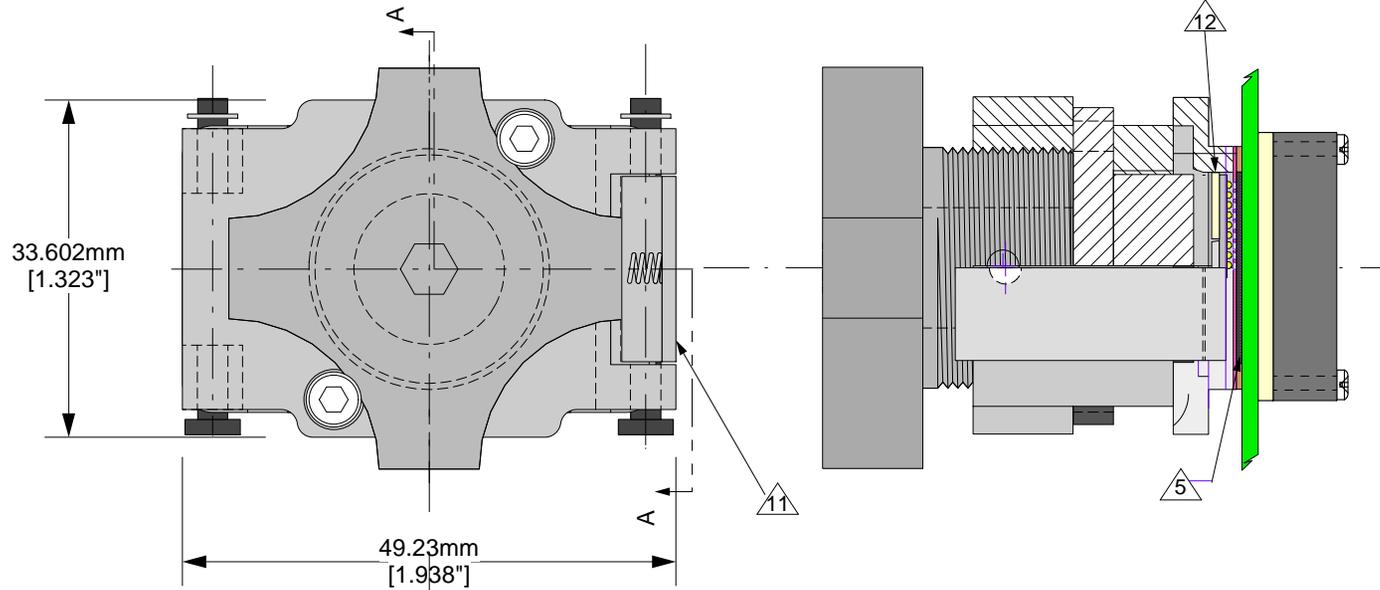
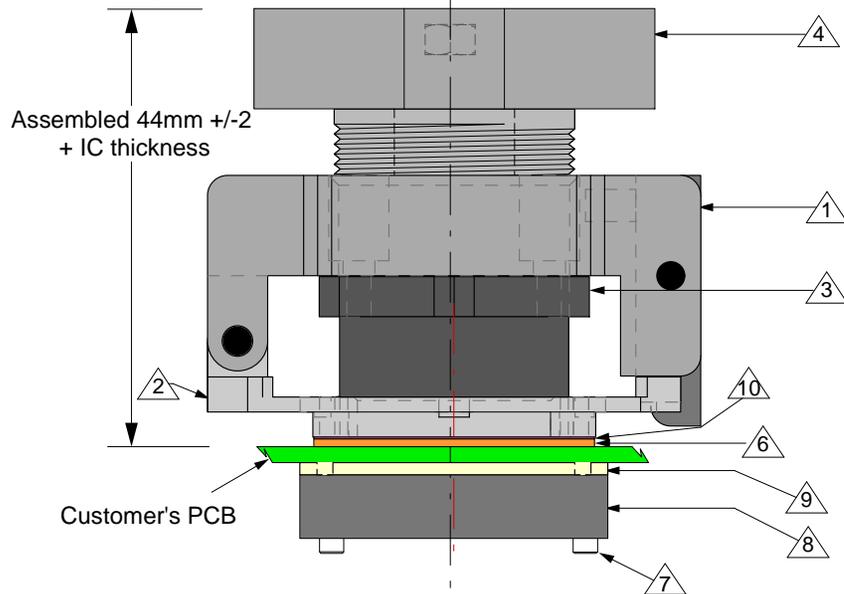


Top View



Side View
(Section AA)



Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

Materials:

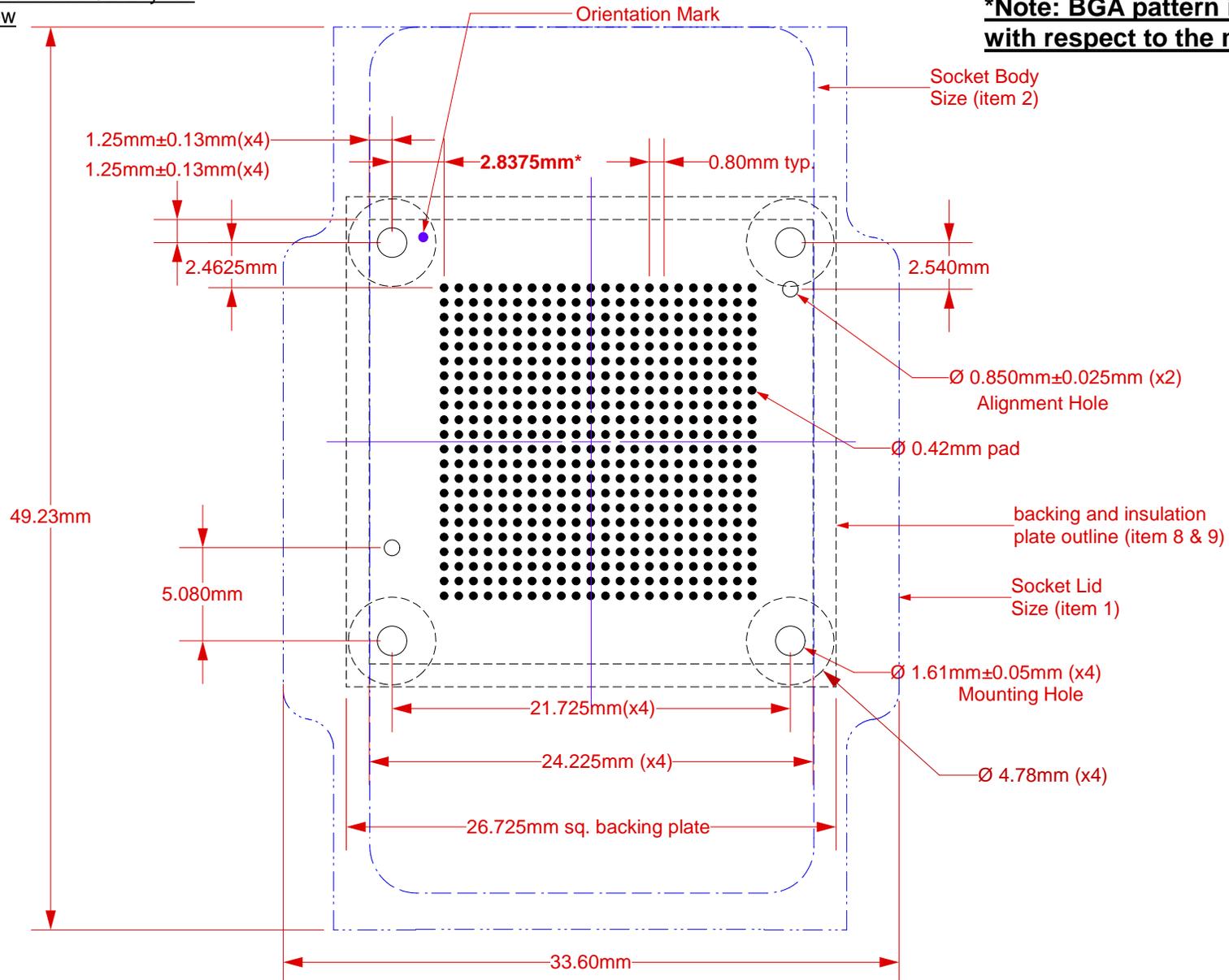
- △1 Clam Shell Lid: Black anodized Aluminum. Height = 20 mm.
- △2 Socket Base: Black anodized Aluminum. Height = 6 mm.
- △3 Compression Plate: Black anodized Aluminum. Thickness = 12 mm.
- △4 Compression Screw: Clear anodized Aluminum. Height = 27 mm, Fluted Knob
Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- △5 Elastomer Guide: Non-clad FR4. Thickness = 0.725mm.
- △6 Socket Base Screw: Socket Head Cap Screw, alloy steel with black oxide finish, 0-80 Thread, 1/2" long.
- △7 Backing Plate: Black anodized Aluminum
- △8 Insulation Plate: Ultem
- △9 Ball Guide: Kapton polyimide.
- △10 Latch: Black anodized Aluminum.
- △11 IC frame: Ultem

| | | | | |
|---|--|-----------------------|---------------|--------|
|  | CG-BGA-4008 Drawing | Status: Released | Scale: 1.25:1 | Rev: A |
| | © 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com | Drawing: Vinayak R | Date: 2/18/10 | |
| | | File: CG-BGA-4008 Dwg | Modified: | |

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

Recommended PCB Layout
Top View

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**



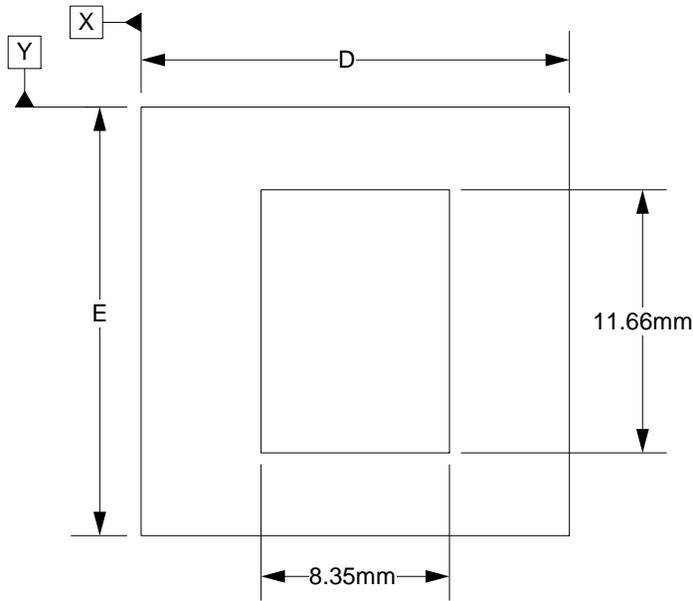
Target PCB Recommendations
Total thickness: 1.5mm min.
Plating: Gold or Solder finish

DXF DATA WILL BE PROVIDED

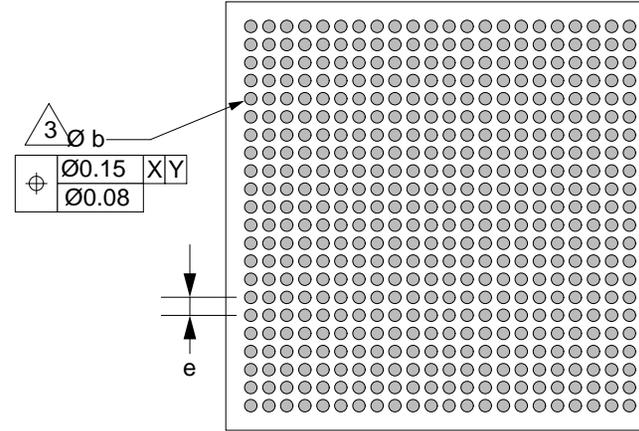
Recommended PCB Layout Tolerances:
±0.025mm [±0.001"] unless stated otherwise.

| | | | | |
|---|--|-----------------------|------------|---------------|
|  | CG-BGA-4008 Drawing | Status: Released | Scale: 3:1 | Rev: A |
| | © 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com | Drawing: Vinayak R | | Date: 2/18/10 |
| | | File: CG-BGA-4008 Dwg | Modified: | |

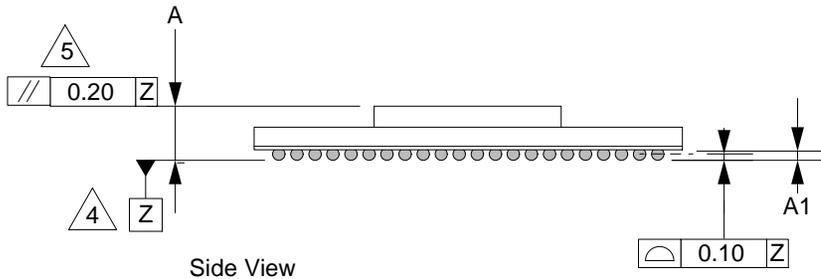
Compatible BGA Spec.



Top View



Bottom View



Side View

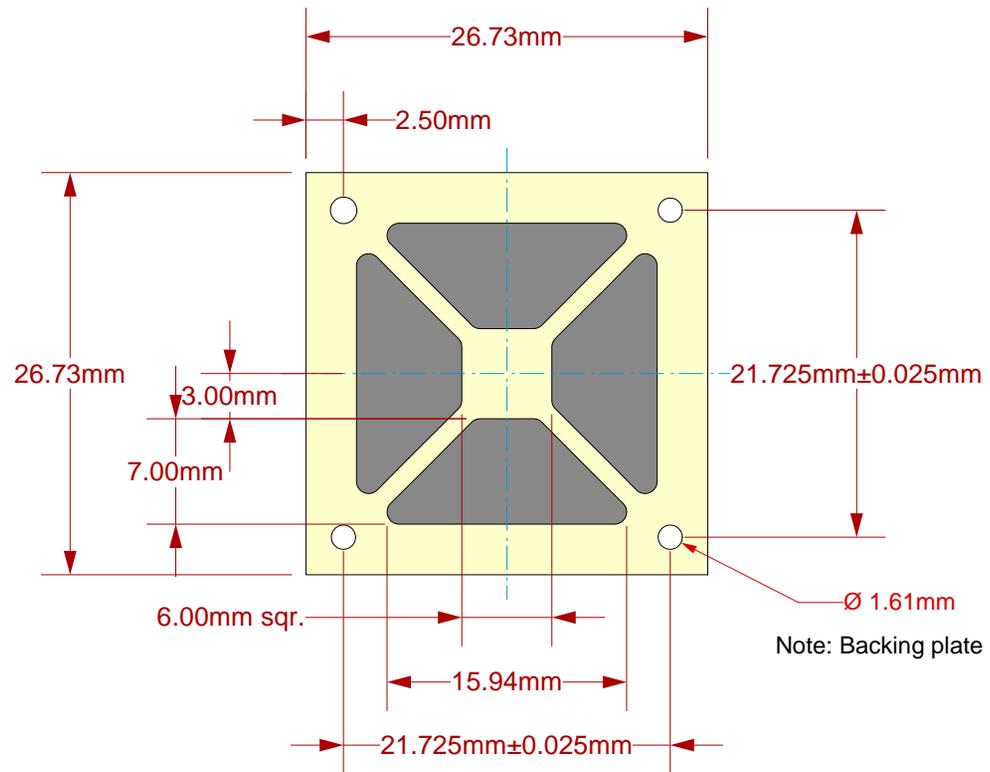
- 1 Dimensions are in millimeters.
- 2 Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5 Parallelism measurement shall exclude any effect of mark on top surface of package.

| DIM | MIN | MAX |
|-----|----------|------|
| A | | 4.00 |
| A1 | 0.36 | 0.46 |
| b | 0.50 | |
| D | 19.0 BSC | |
| E | 19.0 BSC | |
| e | 0.8 BSC | |

Array: 22 X 22

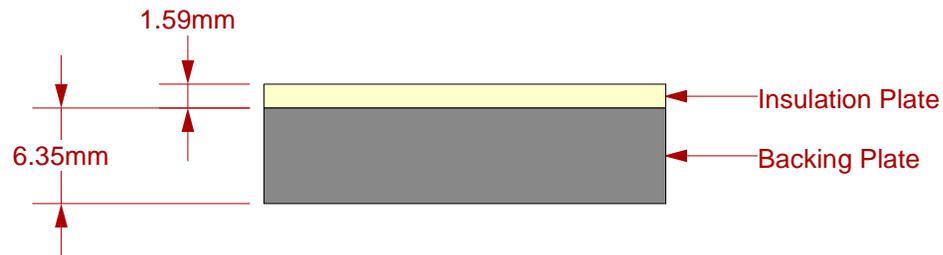
| | | | | |
|---|--|-----------------------|-----------|---------------|
|  | CG-BGA-4008 Drawing | Status: Released | Scale: - | Rev: A |
| | © 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com | Drawing: Vinayak R | | Date: 2/18/10 |
| | | File: CG-BGA-4008 Dwg | Modified: | |

Top View



Note: Backing plate holes are tapped to accept 0-80 screws.

Side View

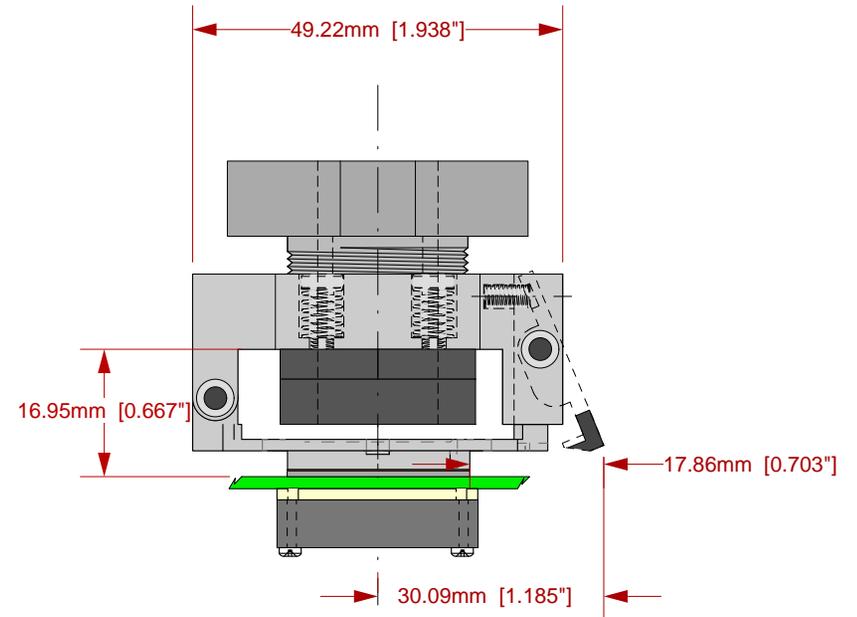
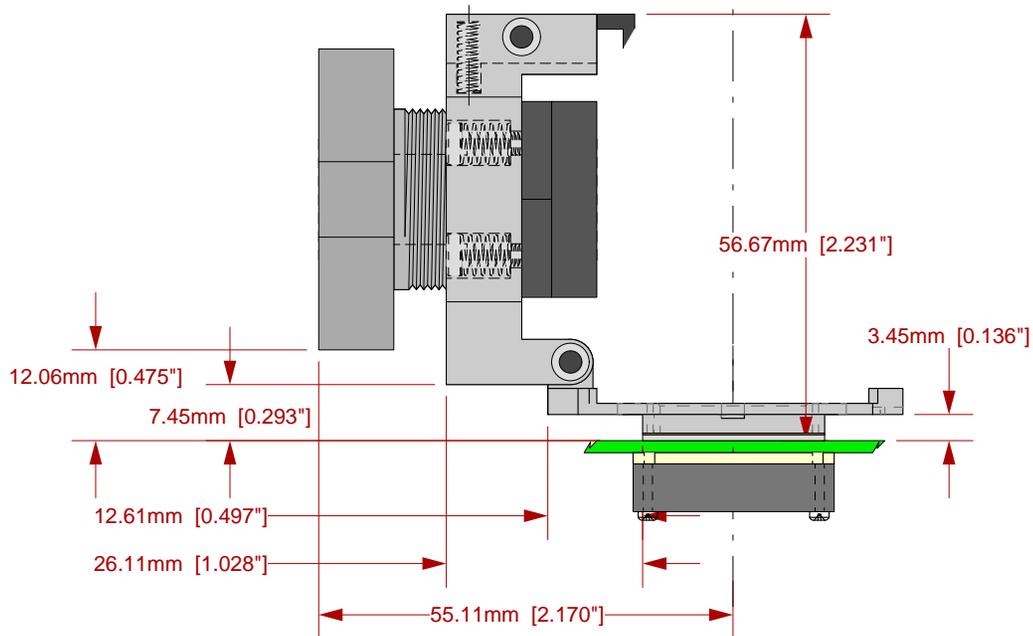
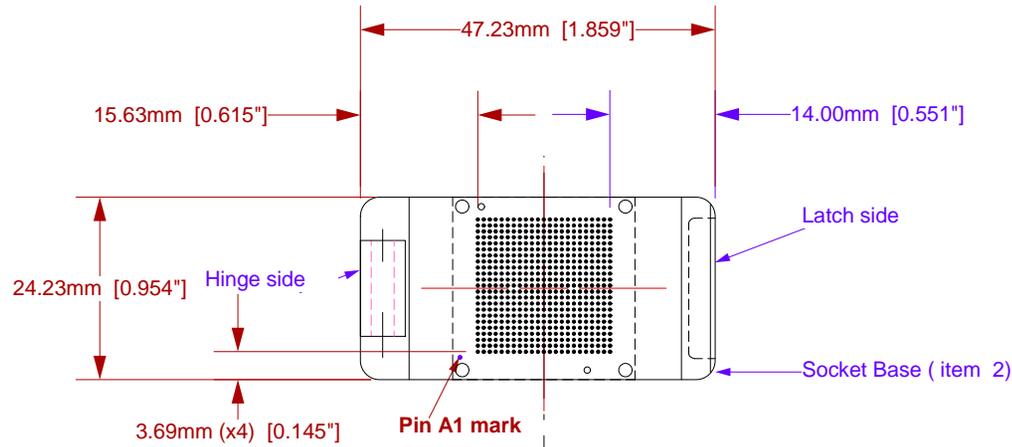


Description: Backing Plate with Insulation Plate

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)

| | | | | |
|---|--|-----------------------|------------|---------------|
|  | CG-BGA-4008 Drawing | Status: Released | Scale: 2:1 | Rev: A |
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| | | File: CG-BGA-4008 Dwg | Modified: | |

Top View of Socket Base



| | | | | |
|---|--|-----------------------|---------------|---------------|
|  | CG-BGA-4008 Drawing | Status: Released | Scale: 1.25:1 | Rev: A |
| | © 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com | Drawing: Vinayak R | | Date: 2/18/10 |
| | | File: CG-BGA-4008 Dwg | Modified: | |

All dimensions are in mm.
 All tolerances are +/- 0.125mm.
 (Unless stated otherwise)